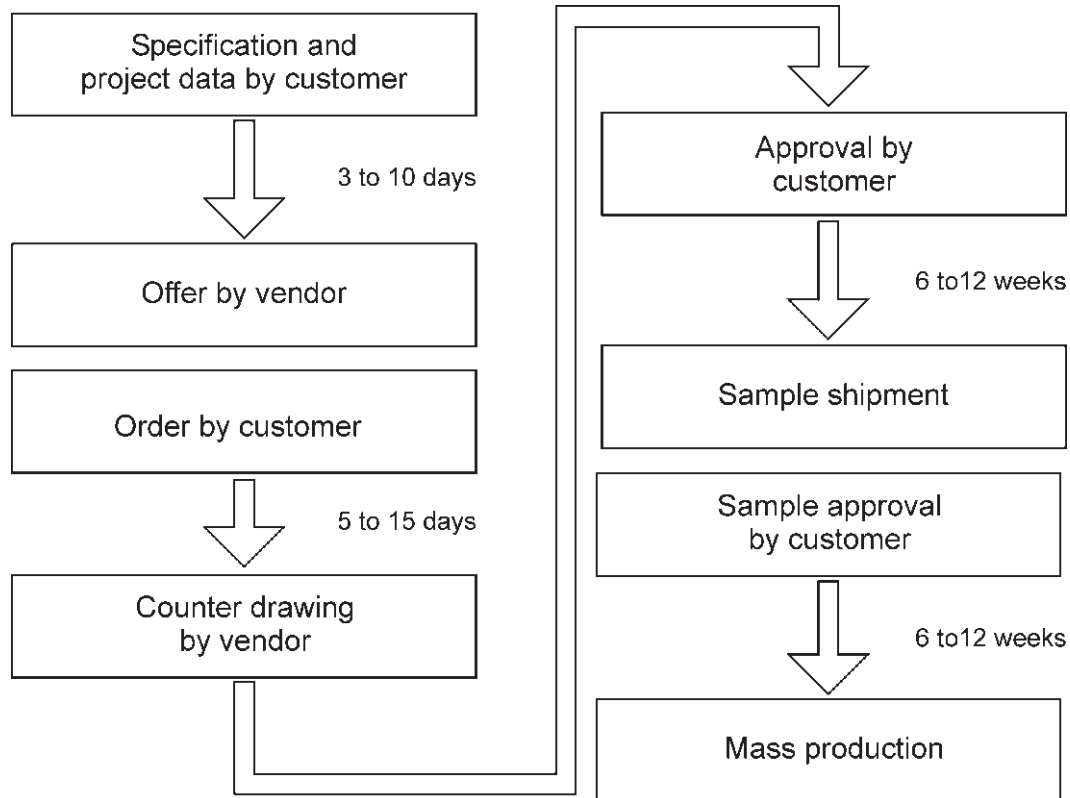


## Project Flowchart



## Glossary

A.A.	active area
BEF	brightness enhancement filter
Bezel	mounting frame
CCFL	cold cathode fluorescent lamp
COB	chip on board
COG	chip on glass
DUTY	multiplex
EL	electro luminescent
FFC	flexible film cable
FPC	flexible printed circuit
HS	heat seal
HT	high temperature
ITO	indium tin oxide
LED	light emitting diode
Ledge	contact area on the glass
MUX	multiplex

PCB	printed circuit board
RF	reflective mode
RTV	room temperature vulcanisation
SMT	surface mounted technology
SPI	serial peripheral interface
TAB	tape automated bonding
TC	temperature compensation
TCP	tape carrier package
TF	transflective mode
TM	transmissive mode
Topr	operating temperature
Tstrg	storage temperature
V.A.	viewing area
VLCD	contrast voltage
Zebra	elastomer (rubber) connector
ZIF	zero insertion force